





Epoxy Technology's extensive line of optical adhesives is used for bonding and coating in many applications; most commonly in fiberoptics. Our epoxy adhesives are frequently used to bundle optical fibers and bond components in optoelectronic devices.

Selected Product Listing for EPO-TEK® Optical Adhesives

EPO-TEK®	COLOR Before/After CURE (thin film)	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₉)	LAP SHEAR STRENGTH (PSI)	MODULUS (PSI)	INDEX OF REFRACTION (Nd)	SPECTRAL TRANSMISSION	POT LIFE (@ room temp)
301	Clear / Colorless	65°C – 1 hour 23°C – 24 hours	@ 100 rpm 100 – 200	≥65°C	>2,000	327,463	1.5190	≥99% @ 382 – 980nm ≥97% @ 980 – 1640nm	1-2 hours
301-2	Clear / Colorless	80°C – 3 hours 23°C – 2 days	@ 100 rpm 225 – 425	≥80°C	>2,000	298,719	1.5318	>99% @ 400 – 1200nm >98% @ 1200 – 1600nm	8 hours
301-2FL	Clear / Colorless	80°C – 3 hours 23°C – 3 days	@ 100 rpm 100 – 200	≥45°C	>2,000	152,946	1.5102	>99% @ 400 – 1000nm >97% @ 1000 – 1600nm	10 hours
302	Clear / Light Yellow	23°C – 2 hours	@ 20 rpm 5,000 - 10,000	≥40°C	1,778	153,918	1.5442	>85% @ 440 – 900nm >88% @ 900 – 1600nm	10 min
302-3M	Clear / Colorless	65°C – 3 hours 23°C – 24 hours	@ 100 rpm 800 - 1,600	≥55°C	>2,000	251,532	1.5446	>95% @ 460 – 1620nm	1 hour
305	Clear / Colorless	65°C – 1 hour 23°C – 24 hours	@ 100 rpm 150 – 250	≥35°C	1,880	100,395	1.4763	>91% @ 250nm >98% @ 400 – 1600nm	1 hour
310M-2	Clear / Colorless	65°C – 2 hours 23°C – 24 hours	@ 100 rpm 250 – 325	≥30°C	678	1,936	1.4947	>98% @ 380 – 1660nm	1.5 hours
320	Black / Black	65°C – 2 hours 23°C – 24 hours	@ 100 rpm 700 - 1,200	≥55°C	>2,000	261,271	N/A	<1% @ 300 – 2500nm	1 hour
323LP	Slight Yellow / Red	150°C - 1 hour 90°C - 30 min	@ 50 rpm 3,500 - 5,500	≥100°C	>2,000	444,110	1.5704	>90% @ 640 – 800nm >94% @ 820 – 1620nm	24 hours
353ND	Amber / Dark Red	150°C – 1 min 80°C – 30 min	@ 50 rpm 3,000 - 5,000	≥90°C	>2,000	516,912	1.5694	>98% @ 800 - 1000nm >95% @ 1100 - 1600nm	3 hours
353ND-T	Tan / Dark Red	150°C – 1 min 80°C – 30 min	@ 20 rpm 9,000 - 15,000	≥90°C	1,953	559,120	N/A	N/A	3 hours
354	Amber / Dark Red	150°C – 10 min 80°C – 2 hours	@ 50 rpm 4,000 - 6,000	≥95°C	1,668	356,376	1.5734	>96% @ 600nm >99% @ 800nm	3 days
360	Light Yellow / Dark Amber	150°C — 1 min 100°C — 10 min	@ 100 rpm 350 – 550	≥90°C	>2,000	322,012	1.5345	>97% @ 700 – 1600nm >88% @ 600nm	6 hours
377	Amber / Dark Amber	150°C – 1 hour	@ 100 rpm 150 - 300	≥95°C	1,456	373,622	1.5195	≥90% @ 600nm – 1000nm ≥98% @ 1000 – 1600nm	24 hours
383ND	Amber / Dark Red	150°C – 1 hour 90°C – 30 min	@ 50 rpm 3,500 - 6,000	≥100°C	>2,000	369,039	1.5715	≥90% @ 520 – 1600nm	8 hours
OD1001-67	Cream / Yellow	150°C – 1 hour 125°C – 1 hour	@ 100 rpm 1,400	≥3°C	N/A	111,780	1.5247	≥90% @ 660 – 2100nm	28 days
OD2002	Cloudy Amber / Dark Amber	150°C - 1 hour 100°C - 30 min	@ 5 rpm 24,000 - 42,000	≥140°C	1,570	263,291	1.5728	>98% @ 800 – 1640nm 69% @ 600nm	4 hours

Note: 23°C denotes RT cure

EPO-TEK® 301 Family

The 301 Family of adhesives is clear and colorless. Available in a variety of related formulations for your specific application needs.

Room Temperature Curing* 301, 301-2, 301-2FL, 301-2FL-T, 302, 305, 310M-2

Very Low Viscosity 301, 301-2 & 301-2FL

Low Stress 301-2FL, 301-2FL-T, 302, 305, 310M-2

Long Pot Life 301-2 (8 hrs), 301-2FL (10 hrs)

High Thixotropy 301-2FL-T

EPO-TEK® 353ND Family

The 353ND Family is one of our most popular, well known adhesive product lines. Variations are most easily characterized by three distinct properties:

Long Pot Life 323LP (24 hrs), 354 (3 days) & 383ND (8 hrs)

High Tg OD2002 (high strength, low modulus)

High Thixotropy 323LP-T, 353ND-T, 354-T

Preferred Packaging for EPO-TEK® adhesive products is a single component syringe.

EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
- Ease of use no mixing, less waste, lower environmental impact
- Increased productivity cost effective

OPTICAL

^{*} Faster curing achieved at higher temperatures, see data sheets for alternate cure sch<mark>edules</mark>



Thermally Conductive



EPO-TEK® thermally conductive, electrically insulating epoxies (TCA) are widely used in many high-tech electronic applications for superior performance & thermal management. Properties range from rigid (*providing thermally enhanced circuit protection*) to flexible (*ideal for CTE mismatches*).

Selected Product Listing for EPO-TEK® Thermally Conductive Adhesives

EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₀)	DIE SHEAR STRENGTH @ RT (80 mil X 80 mil)	MODULUS (PSI)	THERMAL CONDUCTIVITY (W/m°K)	SUGGESTED INTERMITTENT OPERATING TEMPERATURE	POT LIFE (@ room temp)
930-4	150°C – 1 hour 80°C – 6 hours	@ 20 rpm 12,000 – 17,000	≥90°C	≥15kg / 5,334psi	607,651	1.70	<325°C	1 day
† H65-175MP	180°C - 1 hour	@ 2.5 rpm 80,000 – 120,000	≥100°C	≥20kg / 7,112psi	816,394	0.80	<300°C	28 days
† H67-MP	150°C - 1 hour	@ 1 rpm 300,000 – 400,000	≥90°C	≥20kg / 7,112psi	641,860	0.50	<300°C	28 days
H70E	150°C - 1 hour 80°C - 90 min	@ 50 rpm 4,000 – 7,000	≥80°C	≥10kg / 3,556psi	787,350	0.90	<300°C	56 hours
H70E-2	150°C – 1 hour 80°C – 90 min	@ 20 rpm 9,000 – 15,000	≥80°C	≥5kg / 1,788psi	1,214,415	1.00	<300°C	2 days
H74	150°C - 1 hour 100°C - 20 min	@ 5 rpm 45,000 – 65,000	≥100°C	≥15kg / 5,334psi	860,430	1.30	<350°C	2 hours
H77	150°C - 1 hour step{100°C - 1 hour+ 120°C - 2 hours	@ 20 rpm 6,000 – 12,000	≥80°C	≥5kg / 1,788psi	950,693	0.70	<350°C	6 hours
T7109	150°C – 1 hour 80°C – 8 hours	@ 20 rpm 14,000 - 20,000	≥45°C	≥15kg / 5,334psi	258,593	0.70	<300°C	4 hours
T7109-19	80°C – 2 hours 23°C – 2 days	@ 5 rpm 40,000 – 70,000	≥40°C	≥5kg / 1,788 psi	29,931	1.30	<250°C	2 hours
T7110	80°C - 2 hours 23°C - 3 days	@ 100 rpm 1,400 – 2,200	≥40°C	≥10kg / 3,556psi	789,250	1.00	<250°C	3.5 hours
T905BN-3	80°C – 2 hours	@ 50 rpm 2,000 – 7,000	≥40°C	≥10kg / 3,556psi	721,520	2.00	<300°C	3 hours
TJ2139-LH	150°C – 1 hour	@ 10 rpm 22,000 – 34,000	≥100°C	≥20kg / 7,112psi	610,418	0.50	<350°C	2.5 days
TV2001	160°C – 5 min 120°C – 30 min	@ 20 rpm 10,000 – 20,000	≥15°C	≥15kg / 5,334psi	16,271	0.40	<325°C	2 days
TZ101	150°C – 1 hour	@ 10 rpm 24,000 – 30,000	≥40°C	≥10kg / 3,556psi	513,778	0.90	<275°C	28 days

Note: 23°C denotes RT cure + MIL-STD 883/5011 certified

High Thermal Management

EPO-TEK® products are unparalleled in their performance for effectively removing heat, providing increased dielectric strength and protecting circuits from hostile environments.

930-4*

- Long Pot Life
- Low Temperature Cure
- Excellent Adhesion To Diverse Substrates
- Small Particle Size (≤20um)

H74*

- Thixotropic Paste
- Low Outgassing
- Superior Chemical & Moisture Resistance
- Medium Particle Size (≤50um)

T905BN-3*

- Low Viscosity
- Self-Leveling
- Ideal For Large Volume Potting & Casting
- Large Particle Size (<300um)

Low Stress/Flex/Compliant

This grouping was specially formulated for stress relieving applications such as: large area bonding, potting and thermal cycling.

T7109-19*

- Low Tg
- Low Modulus
- High Thermal Conductivity
- Room Temperature Curable

TZ101*

- Low Tg & Modulus
- Long Pot Life
- High Strength
- One Component

TV2001

- Very Low Tg
- Low Modulus
- High Strength
- Excellent Adhesion

* Variations of these formulations available

Preferred Packaging for EPO-TEK® adhesive products is a single component syringe.

EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
- Ease of use no mixing, less waste, lower environmental impact
- Increased productivity cost effective







EpoxyTechnology offers a full range of electrically, thermally conductive and mechanical epoxy adhesives (ECA). Our extensive product line allows users to easily select the optimal adhesive for their specific application; based on the best combination of physical, electrical and mechanical characteristics.

Selected Product Listing for EPO-TEK® Electrically Conductive Adhesives

EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₉)	DIE SHEAR STRENGTH @ RT (80 mil X 80 mil)	VOLUME RESISTIVITY (ohm-cm)	THERMAL CONDUCTIVITY (W/m°K)	SUGGESTED INTERMITTENT OPERATING TEMPERATURE	MODULUS (PSI)	POT LIFE (@ room temp)
E2101	150°C – 1 hour	@ 20 rpm 15,000 – 18,000	≥90°C	>5kg / 1,778psi	≤0.0005	2.50	<300°C	1,052,430	5 days
EJ2108	150°C - 1 hour 80°C - 2 hour 23°C - 3 days	@ 10 rpm 11,806	42°C	>8kg / 2,845psi	<0.0009	4.00	<175°C	2,553	1 hour
EJ2189-LV	150°C – 1 hour 23°C – 3 days	@ 1 rpm 25,000 – 45,000	≥40°C	≥10kg / 3,556psi	≤0.009	2.50	<250°C	213,672	4 hours
EJ2312	150°C – 1 hour 23°C – 24 hours	@ 1 rpm 58,822	≥45°C	≥13kg / 4,623psi	≤0.0005	n/a	<250°C	n/a	90 mins
* EK1000	200°C - 30 min step{150°C - 1 hour + 200°C - 1 hour	@ 100 rpm 1,800 – 3,600	≥80°C	>10kg / 3,556psi	≤0.00009	12.60 step{26.30	<300°C	273,528	2 weeks
* H20E	150°C - 45 sec 80°C - 3 hours	@ 100 rpm 2,200 – 3,200	≥80°C	>10kg / 3,556psi	≤0.0004	2.50	<300°C	808,700	2.5 days
H20E-PFC	175°C – 1 hour 80°C – 3 hours	@ 100 rpm 3,000 – 4,000	≥80°C	≥5kg / 1,778psi	≤0.0004	3.20	<325°C	921,254	3 days
H20S	150°C – 1 hour 80°C – 90 min	@ 100 rpm 1,800 – 2,800	≥80°C	≥5kg / 1,778psi	≤0.0005	3.20	<300°C	339,720	3 days
H22	150°C - 1 hour 100°C - 20 mins	@ 20 rpm 12,000 – 20,000	≥100°C	≥5kg / 1,778psi	≤0.005	0.90	<350°C	540,120	16 hours
◆ H35-175MP	180°C - 1 hour 165°C - 1.5 hours	@ 10 rpm 22,000 – 28,000	≥100°C	≥10kg / 3,556psi	≤0.0005	1.50	<300°C	1,106,623	28 days
◆ H37-MP	150°C – 1 hour	@ 10 rpm 22,000 – 26,000	≥90°C	≥10kg / 3,556psi	≤0.0005	1.59	<300°C	727,680	28 days

ed to MIL-31D 003/3011 (MIL) 120L and ER1000 are also available III MIL 918

Adhesive Expert advice at: techserv@epotek.com

Room Temperature Curing

Full Line of products at: epotek.com

EJ2189 Most robust, Room Temperature formulation with superior adhesion

EJ2189-LV Lower viscosity version of EJ2189

EJ2189-VLV Lowest viscosity of EJ2189

EJ2312 Fastest Room Temperature Cure for ECA

Highest Thermal Conductivity/Low Volume Resistivity

Innovative, "Next Generation" ECA's with unsurpassed performance & exceptional thermal management

EK1000 Single component with superior thermal conductivity

EK2000 Two component version of EK1000

EK1000-1 Extended working time version of EK1000 (<7days vs. ≤1day)

EK1000-1-D Enhanced dispensibility

Low Stress/Flex

EJ2108 Medium viscosity, thixotropic paste with low modulus and low temp curable (80°C)

Well Known "Industry Standard" ECA Products

H20E Proven reliability for 40+ years

H20E-FC Fastest curing version

H20E-HC High thermal conductivity

H20E-PFC Optimal rheology for screen/stencil printing

H20S Smooth consistency, designed for die stamping & dispensing

H20E-D/H20S-D/H20E-PFC-D Single component versions with enhanced dispensability

Preferred Packaging for EPO-TEK® adhesive products is a single component syringe.

EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
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- Increased productivity cost effective

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EPO-TEK® offers an exclusive line of high performance UV curing adhesives based on both epoxy as well as acrylate systems. Our unique UV formulations provide superior performance with short cure times for a wide variety of applications. Many of our novel epoxy/UV formulations can be further enhanced by thermal post curing.

Current Product Listing for EPO-TEK® UV Adhesives

Epoxy-Based

Thermal Post Cure - Increases the degree of conversion; enhancing performance

UV + Thermal Post Cure (typically 80-150°C) for Enhanced Performance

EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₉)	HARDNESS	INDEX OF REFRACTION Nd*	SPECTRAL TRANSMISSION	UV TRANSMISSION % AT 400nm	PERFORMANCE FEATURES
0G116	100mW/cm² @ 240 – 365nm for > 30 sec	@ 2.5 rpm 80,000 - 10,500	≥135°C	n/a	1.5892	89% @ 400nm ≥98% @ 560 – 1660nm	89.310%	Higher viscosity version of OG116-31, high chemical resistance, Tg & index, very high strength
0G116-31	100mW/cm² @ 240 – 365nm for > 30 sec	@ 10 rpm 20,000 – 30,000	≥115°C	83D	1.5842	≥92% @ 500nm ≥96% @ 660 – 1640nm	83.211%	High chemical resistance, high Tg & high index
0G142-87	100mW/cm² @ 240 – 365nm for > 30 sec	@ 100 rpm 250 – 600	≥100°C	82D	1.5058	>97% @ 580 – 1660nm	83.110%	Low viscosity, excellent bond strength, moisture resistance
0G142-95	100mW/cm² @ 240 – 365nm for > 2 min	@ 100 rpm 534	N/A	82D	1.5123	≥97% @ 580 – 1680nm	83.110%	Low viscosity, excellent bond strength, moisture resistance
0G142-112	100mW/cm² @ 240 – 365nm for > 30 sec	@ 100 rpm 1,200 – 1,700	≥90°C	83D	1.5560	>97% @ 500 – 1660nm	80.334%	Medium viscosity, high moisture resistance, exceptional bond strength
0G159-2	100mW/cm² @ 240 – 365nm for > 30 sec	@ 2.5 rpm 100,000 – 140,000	≥30°C	69D	1.5715	≥98% @ 580 – 2000nm	90.847%	Thixotropic, contains 1 mil glass beads, excellent moisture resistance
UJ1190	100mW/cm² @ 240 – 365nm for > 60 sec	@ 100 rpm 501	100°C	80D	1.4993	≥80% @ 380 - 2440nm ≥94% @ 520 - 1560nm	86.567%	Low viscosity, good for thick sections
UD1355	100mW/cm² @ 240 – 365nm for > 90 sec	@ 100 rpm 447	36°C	77D	1.4925	≥96% @ 800 – 2200nm ≥99% @ 360 – 780nm	99.921%	Optically clear, low viscosity, resists discoloration during solder reflow

UV + Thermal Post Cure (Typically 80-150°C) for Shadow Curing <5mm shadow cure with proper thermal cure

EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₉)	HARDNESS	INDEX OF REFRACTION Nd*	SPECTRAL TRANSMISSION	PERFORMANCE FEATURES
† 0G198-54	100mW/cm² @ 240 – 365nm for > 30 sec	@ 100 rpm 200 – 450	131°C	86D	1.5256	≥97% @ 460 – 1680nm	Low viscosity, high Tg, excellent bond strength
† 0G198-55	100mW/cm² @ 240 – 365nm for > 30 sec	@ 100 rpm 1,200 – 2,000	>120°C	85D	1.5196	≥97% @ 560 – 1680nm	Thixotropic, high viscosity, high Tg

^{*} Cured index measured at 589nm † 150°C/1 hour to cure shadowed areas optional

UV Cure	UV Cure Only									
EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₀)	HARDNESS	INDEX OF REFRACTION Nd*	SPECTRAL TRANSMISSION	PERFORMANCE FEATURES			
0G133-7	100mW/cm ² @ 320 – 500nm for > 2 min	@ 100 rpm 150 – 450	≤10°C	81A	1.5060	≥90% @ 440 - 580nm ≥96% @ 800 - 1600nm	Low viscosity, flexible, high flow version of OG133-8			
0G133-8	100mW/cm² @ 240 – 365nm for > 90 sec	@ 100 rpm 1,000 – 1,500	≤10°C	65A	1.5244	≥90% @ 580 - 800nm ≥95% @ 820 - 1660nm	Thixotropic, low Tg & hardness, excellent flexibility			
0G142	100mW/cm² @ 240 – 365nm for > 30 sec	@ 20 rpm 9,000 – 15,000	≥95°C	86D	1.5809	≥92% @ 440 - 620nm ≥97% @ 660 - 1640nm	Medium viscosity, high strength, moisture resistance			
0G154-1	100mW/cm² @ 240 – 365nm for > 30 sec	@ 5 rpm 26,000 – 34,000	128°C	80D	1.5692	97% @ 500 – 1660nm	High viscosity, high Tg, low modulus			
* Cured index measured at 589nm										

Full Line of products at: epotek.com

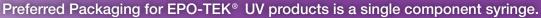
UV Adhesive Expert advice at: techserv@epotek.com

Agrylate-Based

UV Cure Only

EPO-TEK®	CURE CONDITIONS (minimal)	VISCOSITY @ 23°C (cPs)	GLASS TRANSITION TEMPERATURE (T ₀)	HARDNESS	INDEX OF REFRACTION Nd*	SPECTRAL TRANSMISSION	PERFORMANCE FEATURES
0G603	100mW/cm² @ 240 – 365nm for > 5 sec	@ 100 rpm 150 – 250	≥70°C	84D	1.5037	≥98% @ 420 – 1600nm	Low viscosity, fast cure
0G653	100mW/cm² @ 240 – 365nm for > 1 sec	@ 100 rpm 650 – 850	65°C	76D	1.5106	≥83% @ 380nm ≥97% @ 440 – 2220nm	Low viscosity, green colored, light blocking properties, very fast cure (1-3 sec @ 365nm)
0G675	100mW/cm² @ 240 – 365nm for > 2 sec	@ 100 rpm 2,000 – 5,000	≥5°C	70A	1.4790	≥98% @ 400 – 1660nm	Medium viscosity, fast cure, low Tg

* Cured index measured at 589nm



EPO-TEK® syringes offer many advantages:

- Increased reliability and consistency
- Ease of use no mixing, less waste, lower environmental impact
- Increased productivity cost effective







UV Hybrid



EpoxyTechnology has developed a line of unique epoxy-based, UV Hybrid chemistry adhesives. These new, "state-of-the-art" formulations allow for improved handling and process control by utilizing both UV and thermal curing. Tacking can be done in seconds, followed up by heat; giving both speed and strength to the process.

Current Product Listing for EPO-TEK® UV Hybrid Adhesives

	HYB-353ND-LV	HYB-353ND	HYB-353ND-HV	HYB-353ND-TX2	HYB-353ND-TX3					
Description	Low viscosity, fast tack	Viscosity match of 353ND	Higher viscosity version	Thixo version TI = 1.6	Thixo version TI = 1.3					
Viscosity (@10 rpm)	800 - 2,000 cPs	3,000 - 7,000 cPs	9,000 - 20,000 cPs	20,000 - 30,000 cPs	25,000 - 41,000 cPs					
Pot Life	<20 hrs	<2 hrs	2 hrs	<2 days	<2 days					
Tg (°C)	≥80	≥100	≥100	≥90	≥80					
Cure Condition	UV 10 sec @ 100mW/cm² +150°C/30min	UV 10 sec @ 100mW/cm² +150°C/30min	UV 10 sec @ 100mW/cm² +150°C/30min	UV 10 sec @ 100mW/cm² +150°C/30min	UV 10 sec @ 100mW/cm² +150°C/30min					
	Lower temperature cures, (≥80°C) are possible depending upon application									
Degradation Temp (°C)	400	400	388	410	399					
Weight Loss	0.08%	0.06%	non detectable	0.05%	0.19%					
Die Shear	≥15kg / 5,334psi	≥20kg / 7,112psi	≥25kg / 8,890psi	≥15kg / 5,334psi	≥15kg / 5,334psi					
Spectral Transmission	≥95% @ 1100-1600nm ≥98% @ 800-1000nm	≥95% @ 1100-1600nm ≥98% @ 800-1000nm	≥95% @ 1100-1600nm ≥98% @ 800-1000nm	≥95% @ 1100-1600nm ≥98% @ 800-1000nm	≥95% @ 1100-1600nm ≥98% @ 800-1000nm					
*Index of Refraction	1.5215	1.5259	1.5545	†N/M	†N/M					
* uncured at 589nm - † not measured										

Benefits of a UV Hybrid

- Overall process improvement
- Lower stress and less shrinkage
- Increased thru-put on expensive alignment machines
- Easier handling
- Tack free in seconds
- 85°C/85%RH resistance, comparable to 353ND

UV Hybrid Development

Additional UV Hybrid products are in development and testing; including Room Temperature Cure and Thermally Conductive Hybrids.

Contact our Adhesive Experts at techserv@epotek.com for more information on our latest product offerings.

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EPO-TEK®'s Specialty Adhesive Products + Advanced Packaging Techniques Premium Adhesive Performance

EpoxyTechnology Inc. is a global leader in formulating, manufacturing and packaging specialty adhesive. We have worldwide *Certified Packaging Centers of Excellence* in North America, Europe and Asia.

Our specialty formulated adhesives are packaged with meticulous attention to specifications in the following packaging options:



- Premixed and Frozen (PMF) Syringes
 - Room Temperature Stabilized Syringes
 - Bi-Paks



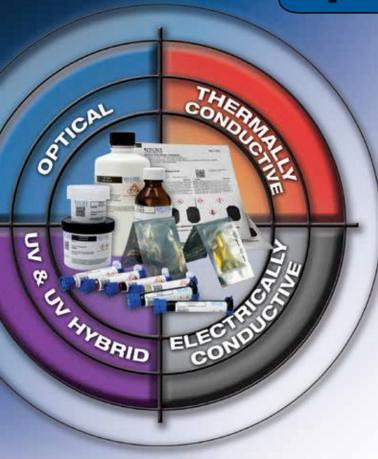
- Increased Reliability/Consistency/Uniformity
 - -Precise Mix Ratio, Lot to Lot
- Cost Effective
 - -Time Saving in Preparation of Material, Increased Productivity
- Less Exposure to Chemical Hazards, Reduced Waste, and Lower Environmental Impact
- Ease of Use
 - -Convenient, No Measuring, No Mixing, Ready to Use, Stress Free





Epoxy Technology

epotek.com



Epoxy Technology Inc. (EPO-TEK®) is a global leader in adhesives since 1966. We have a full line of Specialty Optical, Thermally Conductive (TCA), Electrically Conductive (ECA), UV and UV Hybrid Adhesives.

This **Selector Guide** lists many, but not all, of our 300+ products. The adhesives listed in this guide showcase many of our newest, as well as our best known products. A complete listing can be found at: epotek.com.

In addition to our regular catalog products, we offer an extensive line of tested and certified biocompatible / medical device grade adhesives, known as our **MED line**. Please visit www.epotek.com/medical for more details.

We also offer Custom Formulation Services by a dedicated team of experienced formulators.

Our **Adhesive Experts** are readily available for technical discussions and will assist in finding the best adhesive solution.

Contact them at: +1.978.667.3805 & **techserv@epotek.com**, for recommendations or to schedule a visit.

ORDERING INFO

USA

Contact Customer Service at: 978.667.3805 or customerservice@epotek.com

International

We sell through EPO-TEK® trained & authorized distributors. Visit: epotek.com/site/reps.html for a complete listing of our agents.











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